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Intel Announces New Packaging and Test Technologies for Foundry Customers

New Technologies to Improve Time to Market and Reduce Costs

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Intel Corporation today announced two new technologies for Intel Custom Foundry customers that need cost-effective advanced packaging and test technologies.

Embedded Multi-die Interconnect Bridge (EMIB), available to 14nm foundry customers, is a breakthrough that enables a lower cost and simpler 2.5D packaging approach for very high density interconnects between heterogeneous dies on a single package. Instead of an expensive silicon interposer with TSV (through silicon via), a small silicon bridge chip is embedded in the package, enabling very high density die-to-die connections only where needed. Standard flip-chip assembly is used for robust power delivery and to connect high-speed signals directly from chip to the package substrate. EMIB eliminates the need for TSVs and specialized interposer silicon that add complexity and cost.

“The EMIB technology enables new on-package functionality that may have been too costly to pursue with previous solutions,” said Babak Sabi, Intel vice president and director, Assembly and Test Technology Development.

Intel also announced the availability of its revolutionary High Density Modular Test (HDMT) platform. HDMT, a combination of hardware and software modules, is Intel’s test technology platform that targets a range of products in diverse markets including server, client, system on chip, and Internet of Things. Until now, this capability was only available internally for Intel products. Today’s announcement makes HDMT available to customers of Intel Custom Foundry.

“We developed the HDMT platform to enable rapid test development and unit-level process control. This proven capability significantly reduces costs compared to traditional test platforms. HDMT reduces time to market and improves productivity as it uses a common platform from low-volume product debug up to high-volume production,” said Sabi.

EMIB is available to foundry customers for product sampling in 2015 and HDMT is available immediately.

About Intel

Intel (NASDAQ:INTC) is a world leader in computing innovation. The company designs and builds the essential technologies that serve as the foundation for the world’s computing devices. As a leader in corporate responsibility and sustainability, Intel also manufactures the world’s first commercially available “conflict-free” microprocessors. Additional information about Intel is available at newsroom.intel.com and blogs.intel.com, and about Intel’s conflict-

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